

Electronic Patent Application Fee Transmittal

Application Number:	10807417			
Filing Date:	23-Mar-2004			
Title of Invention:	Microcap wafer bonding apparatus			
First Named Inventor/Applicant Name:	R. Shane Fazzio			
Filer:	Thomas F. Woods			
Attorney Docket Number:	10030899-1			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	540	540
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				540